## PMP4460 BOM 12/2/2014

Item	Qty	Reference	Description	Size	Value	MFR
1	6	C1 C6-10	Capacitor, Ceramic	0805	2.2uF/25V	STD
2	1	C2	Capacitor, Ceramic	0603	10nF/25V	STD
3	1	C3	Capacitor, Ceramic	0603	1uF/16V	STD
4	1	C4	Capacitor, Ceramic	0603	3.3nF/25V	STD
5	1	C5	Capacitor, Ceramic	0603	100nF/25V	STD
6	1	J1	Connector, 100 mil Pitch			STD
7	1	D1	DIODE SML SIG 75V 0.15A SOD323F	SOD-323	1N4148WS	STD
8	1	U1	48 V, 650 mA Constant On-Time Synchronous Buck Regulator	WSON-8	LM25017SD/NOPB	ТІ
9	1	T1	Transformer			MNC
10	1	R1	Resistor, Chip, 1/10W, 1%	0603	160K	STD
11	3	R2	Resistor, Chip, 1/10W, 1%	0603	10K	STD
12	1	R3	Resistor, Chip, 1/10W, 1%	0603	240K	STD
13	1	R4 R7-8	Resistor, Chip, 1/10W, 1%	0603	20K	STD
14	1	R5	Resistor, Chip, 1/10W, 1%	0603	13K	STD
15	1	R6	Resistor, Chip, 1/10W, 1%	0603	1.5K	STD
16	2	D2-3	DIODE SCHOTTKY 40V 0.4A SOD323	SOD-323	ZHCS400	Infineon
17	2	D4-5	Diode, Zener	SOD-323	NA	STD

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